H05K PRINTED CIRCUITS; CASINGS OR CONSTRUCTIONAL DETAILS OF ELECTRIC APPARATUS; MANUFACTURE OF ASSEMBLAGES OF ELECTRICAL COMPONENTS

NOTES

1. This subclass covers:
   • combinations of a radio or television receiver with apparatus having a different main function;
   • printed circuits structurally associated with non-printed electric components.

2. In this subclass, the following expression is used with the meaning indicated:
   • "printed circuits" covers all kinds of mechanical constructions of circuits that consist of an insulating base or support carrying the conductor and are combined structurally with the conductor throughout their length, especially in a two-dimensional plane, the conductors of which are secured to the base in a non-dismountable manner, and also covers the processes or apparatus for manufacturing such constructions, e.g. forming the circuit by mechanical or chemical treatment of a conductive foil, paste, or film on an insulating support.

WARNING

In this subclass non-limiting references (in the sense of paragraph 39 of the Guide to the IPC) may still be displayed in the scheme.

1.00 Printed circuits
1.02 . Details
1.0201 . . {Thermal arrangements, e.g. for cooling, heating or preventing overheating}
1.0203 . . . {Cooling of mounted components (H05K 1/0272 takes precedence)}
1.0204 . . . . {using means for thermal conduction connection in the thickness direction of the substrate (H05K 1/0207 takes precedence)}
1.0206 . . . . {by printed thermal vias}
1.0207 . . . . {using internal conductor planes parallel to the surface for thermal conduction, e.g. power planes}
1.0209 . . . . {External configuration of printed circuit board adapted for heat dissipation, e.g. layout of conductors, coatings}
1.021 . . . . {Components thermally connected to metal substrates or heat-sinks by insert mounting}
1.0212 . . . {Printed circuits or mounted components having integral heating means}
1.0213 . . . {Electrical arrangements not otherwise provided for}
1.0215 . . . {Grounding of printed circuits by connection to external grounding means}
1.0216 . . . . {Reduction of cross-talk, noise or electromagnetic interference (grounding H05K 1/0215)}
1.0218 . . . . {by printed shielding conductors, ground planes or power plane (H05K 1/0236 takes precedence)}
1.0219 . . . . . {Printed shielding conductors for shielding around or between signal conductors, e.g. coplanar or coaxial printed shielding conductors}
1.0221 . . . . . {Coxially shielded signal lines comprising a continuous shielding layer partially or wholly surrounding the signal lines}
1.0222 . . . . . {for shielding around a single via or around a group of vias, e.g. coaxial vias or vias surrounded by a grounded via fence}
1.0224 . . . . {Patterned shielding planes, ground planes or power planes (H05K 1/0253 takes precedence)}
1.0225 . . . . . {Single or multiple openings in a shielding, ground or power plane (H05K 1/0227 takes precedence)}
1.0227 . . . . {Split or nearly split shielding or ground planes}
1.0228 . . . . . {Compensation of cross-talk by a mutually correlated lay-out of printed circuit traces, e.g. for compensation of cross-talk in mounted connectors (balanced signal pairs H05K 1/0245)}
1.023 . . . . {using auxiliary mounted passive components or auxiliary substances (printed passive components H05K 1/16)}
1.0231 . . . . {Capacitors or dielectric substances}
1.0233 . . . . {Filters, inductors or a magnetic substance}
1.0234 . . . . {Resistors or by disposing resistive or lossy substances in or near power planes (H05K 1/0246 takes precedence)}
1.0236 . . . . {Electromagnetic band-gap structures}
1.0237 . . . . {High frequency adaptations (H05K 1/0216 takes precedence)}
1.0239 . . . . {Signal transmission by AC coupling}
H05K

1/024 . . . . [Dielectric details, e.g. changing the dielectric material around a transmission line]
1/0242 . . . . [Structural details of individual signal conductors, e.g. related to the skin effect]
1/0243 . . . . [Printed circuits associated with mounted high frequency components]
1/0245 . . . . [Lay-out of balanced signal pairs, e.g. differential lines or twisted lines]
1/0246 . . . . [Termination of transmission lines]
1/0248 . . . . [Skew reduction or using delay lines]
1/025 . . . . . [Impedance arrangements, e.g. impedance matching, reduction of parasitic impedance (H05K 1/024 and H05K 1/0243 take precedence; for semiconductor devices H01L 23/66)]
1/0251 . . . . . (related to vias or transitions between vias and transmission lines)
1/0253 . . . . . [Impedance adaptations of transmission lines by special lay-out of power planes, e.g. providing openings (H05K 1/0251 takes precedence)]
1/0254 . . . . . [High voltage adaptations; Electrical insulation details; Overvoltage or electrostatic discharge protection (electrostatic discharge protection for electric apparatus in general H05K 9/0067, H05K 9/0079); Arrangements for regulating voltages or for using plural voltages]
1/0256 . . . . . [Electrical insulation details, e.g. around high voltage areas]
1/0257 . . . . . [Overvoltage protection]
1/0259 . . . . . . [Electrostatic discharge [ESD] protection]
1/026 . . . . . . . [Spark gaps]
1/0262 . . . . . . [Arrangements for regulating voltages or for using plural voltages]
1/0263 . . . . . [High current adaptations, e.g. printed high current conductors or using auxiliary non-printed means; Fine and coarse circuit patterns on one circuit board (H05K 1/0293 takes precedence)]
1/0265 . . . . . [characterized by the lay-out of or details of the printed conductors, e.g. reinforced conductors, redundant conductors, conductors having different cross-sections]
1/0266 . . . . . . [Marks, test patterns, inspection means or identification means]
1/0268 . . . . . . [for electrical inspection or testing]
1/0269 . . . . . . . [for visual or optical inspection]
1/0271 . . . . . . . . . . . (Arrangements for reducing stress or warp in rigid printed circuit boards, e.g. caused by loads, vibrations or differences in thermal expansion]
1/0272 . . . . . . . . . . . [Adaptations for fluid transport, e.g. channels, holes]
1/0274 . . . . . . . . . . . [Optical details, e.g. printed circuits comprising integral optical means (H05K 1/0269 takes precedence; coupling light guides with opto-electronic components G02B 6/42)]
1/0275 . . . . . . . . . . . [Security details, e.g. tampering prevention or detection]
1/0277 . . . . . . . . . . . [Bendability or stretchability details (H05K 1/038, H05K 3/4691 take precedence)]
1/0278 . . . . . . . . . . . [Rigid circuit boards or rigid supports of circuit boards locally made bendable, e.g. by removal or replacement of material]
1/028 . . . . . . [Bending or folding regions of flexible printed circuits (H05K 1/0283 takes precedence)]
1/0281 . . . . . . [Reinforcement details thereof]
1/0283 . . . . . . [Stretchable printed circuits]
1/0284 . . . . . . [Details of three-dimensional rigid printed circuit boards (H05K 1/119 takes precedence; shaping of the substrate H05K 3/0014)]
1/0286 . . . . . . [Programmable, customizable or modifiable circuits (by programmable non-printed jumper connections H05K 3/222)]
1/0287 . . . . . . [having an universal lay-out, e.g. pad or land grid patterns or mesh patterns]
1/0289 . . . . . . [having a matrix lay-out, i.e. having selectively interconnectable sets of X- conductors and Y-conductors in different planes]
1/029 . . . . . . [having a programmable lay-out, i.e. adapted for choosing between a few possibilities]
1/0292 . . . . . . [having a modifiable lay-out, i.e. adapted for engineering changes or repair (H05K 1/0293 takes precedence)]
1/0293 . . . . . . [Individual printed conductors which are adapted for modification, e.g. fusible or breakable conductors, printed switches.]
1/0295 . . . . . . [adapted for choosing between different types or different locations of mounted components]
1/0296 . . . . . . [Conductive pattern lay-out details not covered by sub groups H05K 1/02 - H05K 1/0295 (H05K 1/11 takes precedence; lay-out adapted to mounted component configuration H05K 1/18)]
1/0298 . . . . . . [Multilayer circuits]
1/03 . . . . . . . [Use of materials for the substrate]
1/0306 . . . . . . . [Inorganic insulating substrates, e.g. ceramic, glass]
1/0313 . . . . . . . [Organic insulating material]
1/032 . . . . . . . . . . . [consisting of one material]

NOTE
In this group, in the absence of an indication to the contrary, a material is classified in the last appropriate place

1/0326 . . . . . . [containing O]
1/0333 . . . . . . [containing S]
1/034 . . . . . . . [containing halogen]
1/0346 . . . . . . [containing N]
1/0353 . . . . . . [consisting of two or more materials, e.g. two or more polymers, polymer + filler + reinforcement]
1/036 . . . . . . [Multilayers with layers of different types]
1/0366 . . . . . . [reinforced, e.g. by fibres, fabrics (H05K 1/036 takes precedence)]
1/0373 . . . . . . [containing additives, e.g. fillers (H05K 1/036 takes precedence)]
1/038 . . . . . . [Textiles (used as reinforcing materials for organic insulating substrates H05K 1/0366)]
1/0386 . . . . . . [Paper sheets (used as reinforcing materials for organic insulating substrates H05K 1/0366)]
1/0393 . . . . . . [Flexible materials (H05K 1/038 takes precedence; specific organic compositions are classified in H05K 1/0313 and subgroups)]
1/05 . . . . . . [Insulated {conductive substrates, e.g. insulated} metal substrate]
1/113 . . . {Via provided in pad; Pad over filled via}
1/114 . . . . {Pad being close to via, but not surrounding the via}
1/115 . . . . {Via connections; Lands around holes or via connections (H05K 1/112 takes precedence)}
1/116 . . . . {Lands, clearance holes or other lay-out details concerning the surrounding of a via}
1/117 . . . . {Pads along the edge of rigid circuit boards, e.g. for pluggable connectors}
1/118 . . . . {specially for flexible printed circuits, e.g. using folded portions}
1/119 . . . . {Details of rigid insulating substrates therefor, e.g. three-dimensional details (H05K 1/117 takes precedence)}
1/14 . . . . Structural association of two or more printed circuits (providing electric connection to or between printed circuits H05K 1/11, H01R 12/00)
1/141 . . . . {One or more single auxiliary printed circuits mounted on a main printed circuit, e.g. modules, adapters (H05K 1/142 and H05K 1/147 take precedence)}
1/142 . . . . {Arrangements of planar printed circuit boards in the same plane, e.g. auxiliary printed circuit insert mounted in a main printed circuit}
1/144 . . . . {Stacked arrangements of planar printed circuit boards}
1/145 . . . . {Arrangements wherein electric components are disposed between and simultaneously connected to two planar printed circuit boards, e.g. Cordwood modules}
1/147 . . . . {at least one of the printed circuits being bent or folded, e.g. by using a flexible printed circuit (H05K 1/148 takes precedence)}
1/148 . . . . {Arrangements of two or more hingely connected rigid printed circuit boards, i.e. connected by flexible means}
1/16 . . . . incorporating printed electric components, e.g. printed resistor, capacitor, inductor
1/162 . . . . {incorporating printed capacitors}
1/165 . . . . {incorporating printed inductors}
1/167 . . . . {incorporating printed resistors}
1/18 . . . . Printed circuits structurally associated with non-printed electric components ((H05K 1/0201, H05K 1/023, H05K 1/0243, ) H05K 1/16 take precedence)
1/181 . . . . {associated with surface mounted components}
1/182 . . . . {associated with components mounted in the printed circuit board, e.g. IMC (insert mounted components)}
1/183 . . . . {Components mounted in and supported by recessed areas of the printed circuit board}
1/184 . . . . {Components including terminals inserted in holes through the printed circuit board and connected to printed contacts on the walls of the holes or at the edges thereof or protruding over or into the holes}
1/185 . . . . {Components encapsulated in the insulating substrate of the printed circuit or incorporated in internal layers of a multilayer circuit (semiconductor chips encapsulated by interconnect and support structures H01L 23/5389, H01L 24/00)}
1/186 . . . . {manufactured by mounting on or connecting to patterned circuits before or during embedding}
1/187 . . . . . {the patterned circuits being prefabricated, which are not yet attached to a permanent insulating substrate, e.g. on a temporary carrier}
1/188 . . . . . {manufactured by mounting on or attaching to a structure having a conductive layer, e.g. a metal foil, such that the terminals of the component are connected to or adjacent to the conductive layer before embedding, and by using the conductive layer, which is patterned after embedding, at least partially for connecting the component}
1/189 . . . . . {characterised by the use of a flexible or folded printed circuit (H05K 3/326 takes precedence)}
surface of the insulating support and is thereafter in which the conductive material is applied to the substrate, or temporarily stacked circuit boards (H05K 3/0052) reinforcement}

{Processing two or more printed circuits takes precedence}

{Filling or covering plated through-holes or blind e.g. printed circuit boards, H05K 13/00 manufacturing assemblages of electric components, means therefor (apparatus specially adapted for}

{Apparatus for treatments of printed circuits; conveyors and holding}

{characterised by the composition of the mask}

{characterised by the method of application or removal of the mask (H05K 3/0091 takes precedence)}

{characterised by the exposure method of radiation-sensitive masks}

{Apparatus for treatments of printed circuits with liquids not provided for in groups}

{by semi-additive methods; masks therefor (characterised by metallic etch mask H05K 3/062; electroplating methods or apparatus H05K 3/241)}

{using [thick film techniques, e.g.] printing techniques to apply the conductive material (or similar techniques for applying conductive paste or ink patterns)}

{pretreatment of the circuit board, e.g. modifying wetting properties: Patterning by using affinity patterns (providing shape patterns H05K 3/1258; adhesion treatments H05K 3/38)}

{by screen printing or stencil printing}

{Screens or stencils; Holders therefor}

{Methods or means for supplying the conductive material and for forcing it through the screen or stencil}

{by ink-jet printing or drawing by dispensing}

{by ink-jet printing}

{by using a substrate provided with a shape pattern, e.g. grooves, banks, resist pattern}

{by electrographic or magnetographic printing}

{by other printing techniques, e.g. letterpress printing, intaglio printing, lithographic printing,}

{by other printing techniques, e.g. letterpress printing, intaglio printing, lithographic printing, offset printing}

{After-treatment of the printed patterns, e.g. sintering or curing methods}

{Firing or sintering at relative high temperatures for patterns on inorganic boards, e.g. co-firing of circuits on green ceramic sheets}

{using spraying techniques to apply the conductive material [e.g. vapour evaporation]}

{Masks therefor (H05K 3/048 takes precedence)}
3/146 . . . [By vapour deposition]
3/16 . . . by cathodic sputtering
3/18 . . . using precipitation techniques to apply the conductive material
3/181 . . . [by electroless plating (adhesives therefor H05K 3/387)]
3/182 . . . [characterised by the patterning method]
3/184 . . . . . [using masks]
3/185 . . . . . [by making a catalytic pattern by photoinaging]
3/187 . . . . . [means therefor, e.g. baths, apparatus]
3/188 . . . . . [by direct electroplating]
3/20 . . . by affixing prefabricated conductor pattern ([H05K 1/187, H05K 3/046, H05K 3/4658, H05K 3/4682 takes precedence])
3/202 . . . . . [using self-supporting metal foil pattern]
3/205 . . . . . [using a pattern electroplated or electroformed on a metallic carrier]
3/207 . . . . . [using a prefabricated paste pattern, ink pattern or powder pattern]
3/22 . . . Secondary treatment of printed circuits ([H05K 3/1283 takes precedence; embedding circuits in grooves by pressure H05K 3/107])
3/222 . . . [Completing of printed circuits by adding non-printed jumper connections (printed jumper connections H05K 3/4685)]
3/225 . . . [Correcting or repairing of printed circuits (H05K 1/0292, H05K 3/222, H05K 3/288, H05K 3/4685 take precedence)]
3/227 . . . [Drying of printed circuits]
3/24 . . . Reinforcing the conductive pattern [(by solder coating H05K 3/3457)]
3/241 . . . . . [characterised by the electroplating method; means therefor, e.g. baths or apparatus]
3/242 . . . . . [characterised by using temporary conductors on the printed circuit for electrically connecting areas which are to be electroplated]
3/243 . . . . . [characterised by selective plating, e.g. for finish plating of pads (selective plating for making the circuit pattern H05K 3/108, H05K 3/182)]
3/244 . . . . . [Finish plating of conductors, especially of copper conductors, e.g. for pads or lands (selective plating methods H05K 3/243; finish plating of conductors made by printing techniques H05K 3/246; solder as finish H05K 3/3457, e.g. by plating H05K 3/3473)]
3/245 . . . . . [Reinforcing conductive patterns made by printing techniques or by other techniques for applying conductive pastes, inks or powders; Reinforcing other conductive patterns by such techniques]
3/246 . . . . . . [Reinforcing conductive paste, ink or powder patterns by other methods, e.g. by plating]
3/247 . . . . . . [Finish coating of conductors by using conductive pastes, inks or powders]
3/248 . . . . . . [tired compositions for inorganic substrates]
3/249 . . . . . . [comprising carbon particles as main constituent]
3/26 . . . Cleaning or polishing of the conductive pattern
3/28 . . . Applying non-metallic protective coatings ([H05K 3/0091 takes precedence; methods for intermediate insulating layers for build-up multilayer circuits H05K 3/4673)]
3/281 . . . . . [by means of a preformed insulating foil (H05K 3/284 takes precedence)]
3/282 . . . . . [for inhibiting the insulating foil for preserving the solderability]
3/284 . . . . . [for encapsulating the corrosion of the circuit, e.g. H05K 1/185 takes precedence]
3/285 . . . . . [Permanent coating compositions]
3/287 . . . . . [Photosensitive compositions]
3/288 . . . . . [Removal of non-metallic coatings, e.g. for repairing]
3/30 . . . Assembling printed circuits with electric components, e.g. with resistor
3/301 . . . . . [by means of a mounting structure (H05K 3/325 takes precedence)]
3/303 . . . . . [Surface mounted components, e.g. affixing before soldering, aligning means, spacing means (H05K 3/32 takes precedence)]
3/305 . . . . . [Affixing by adhesive]
3/306 . . . . . [Lead-in-hole components, e.g. affixing or retention before soldering, spacing means (H05K 3/32 takes precedence)]
3/308 . . . . . [Adaptations of leads (connectors to printed circuits H01R 12/00)]
3/32 . . . . . . [electrically connecting electric components or wires to printed circuits]
3/321 . . . . . . [by conductive adhesives]
3/323 . . . . . . [by applying an anisotropic conductive adhesive layer over an array of pads]
3/325 . . . . . . [by abutting or pinching, i.e. without alloying process; mechanical auxiliary parts therefor (adaptations of leads inserted in holes for press-fit connections H05K 3/308)]
3/326 . . . . . . [the printed circuit having integral resilient or deformable parts, e.g. tabs or parts of flexible circuits (H05K 3/365 takes precedence)]
3/328 . . . . . . [by welding]
3/34 . . . . . . by soldering
3/3405 . . . . . [Edge mounted components, e.g. terminals]
3/341 . . . . . . [Surface mounted components]
3/3415 . . . . . . [on both sides of the substrate or combined with lead-in-hole components]
3/3421 . . . . . . [Lead components]
3/3426 . . . . . . . [characterised by the leads]
3/3431 . . . . . . [Leadless components]
3/3436 . . . . . . . [having an array of bottom contacts, e.g. pad grid array or ball grid array components]
3/3442 . . . . . . . [having edge contacts, e.g. leadless chip capacitors, chip carriers]
3/3447 . . . . . . . [Lead-in-hole components (H05K 3/3415 takes precedence)]
3/3452 . . . . . . [Solder masks]
3/3457 . . . . . . [Solder materials or compositions; Methods of application thereof]
3/3463 . . . . . . [Solder compositions in relation to features of the printed circuit board or the mounting process]
3/3468 . . . . . . . [Applying molten solder]
3/3473 . . . . . . . [Plating of solder]
connections to or between printed circuits 

substrate and the metal

Improvement of the adhesion between the insulating circuits (H05K 7/142 takes precedence)

Assembling printed circuits with other printed circuits (H05K 7/142 takes precedence)

by soldering

by abutting, i.e. without alloying process

substantially perpendicularly to each other (H05K 3/361 takes precedence)

(parallel to each other (H05K 3/361 takes precedence)

Improvement of the adhesion between the insulating substrate and the metal

by special treatment of the substrate

by special treatment of the metal

by microetching

by plating

by conversion of the surface of the metal, e.g. by oxidation, whether or not followed by reaction or removal of the converted layer

by the use of an organic polymeric bonding layer, e.g. adhesive

for electroless plating (H05K 3/4661 takes precedence)

by the use of a metallic or inorganic thin film adhesion layer

by the use of a coupling agent, e.g. silane

Forming printed elements for providing electric connections to or between printed circuits

Surface contacts, e.g. bumps (H05K 3/4092 takes precedence; deposition of finish layers on pads H05K 3/24; forming solder bumps H05K 3/3477)

[Applying solder paste, particles or powder (screen printing or stencil printing of solder paste H05K 3/1216)]

Composition of fluxes; Methods of application thereof; Other methods of activating the contact surfaces

[Heatig methods for reflowing of solder (using integral heating means H05K 1/0212)]

Assembling printed circuits with other printed circuits (H05K 7/142 takes precedence)

by thick-film techniques

for via connections in inorganic insulating substrates)

by thin-film techniques

by deforming at least one of the conductive layers

[Integral conductive tabs, i.e. conductive parts partly detached from the substrate]
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5/0026 . . . [provided with connectors and printed circuit boards [PCB], e.g. automotive electronic control units]
5/003 . . . [having an integrally preformed electronic control unit]
5/0034 . . . [having an overmolded housing covering the PCB]
5/0039 . . . [having a tubular housing wherein the PCB is inserted longitudinally]
5/0043 . . . [comprising a frame housing mating with two lids wherein the PCB is flat mounted on the frame housing]
5/0047 . . . [having a two-part housing enclosing a PCB]
5/0052 . . . [characterized by joining features of the housing parts]
5/0056 . . . [characterized by features for protecting electronic components against vibration and moisture, e.g. potting, holders for relatively large capacitors]
5/006 . . . [characterized by features for holding the PCB within the housing]
5/0065 . . . [wherein modules are associated together, e.g. electromechanical assemblies, modular structures]
5/0069 . . . [having connector relating features for connecting the connector pins with the PCB or for mounting the connector body with the housing]
5/0073 . . . [having specific features for mounting the housing on an external structure]
5/0078 . . . [specially adapted for acceleration sensors, e.g. crash sensors, airbag sensors]
5/0082 . . . [specially adapted for transmission control units, e.g. gearbox controllers]
5/0086 . . . [portable, e.g. battery operated apparatus (casings for switching devices H01H 9/02)]
5/0091 . . . [Housing specially adapted for small components (for resistors H01C; for capacitors H01G; for integrated circuits H01L 23/00)]
5/0095 . . . [hermetically-sealed]
5/02 . . . Details
5/0204 . . . [Mounting supporting structure on the outside of casings (mounting supporting structure in casings H05K 7/14)]
5/0208 . . . [Interlock mechanisms; Means for avoiding unauthorised use or function, e.g. tamperproof]
5/0213 . . . [Thermal insulation; Venting means; Condensation eliminators]
5/0217 . . . [Mechanical details of casings (G06F 1/1613, H01M 2/10, H04M 1/0202 take precedence)]
5/0221 . . . [Locks; Latches]
5/0226 . . . [Hinges (H02B 1/38 takes precedence)]
5/023 . . . [Handles; Grips]
5/0234 . . . [Feet; Stands; Pedestals, e.g. wheels for moving casing on floor]
5/0239 . . . [Lids; Hoods, e.g. members for covering aperture]
5/0243 . . . [for decorative purposes]
5/0247 . . . [Electrical details of casings, e.g. terminals, passages for cables or wiring]
5/0252 . . . [Labels, e.g. for identification, markings or configuration store]
5/0256 . . . [of interchangeable modules or receptacles therefor, e.g. cartridge mechanisms]
5/026 . . . [having standardized interfaces (flash memory cards G06K 19/077)]

5/00 . . . Casing, cabinets or drawers for electric apparatus
5/0004 . . . [comprising several parts forming a closed casing]
5/0008 . . . [assembled by screws]
5/0013 . . . [assembled by resilient members]
5/0017 . . . [with display or control units]
5/0021 . . . [Side-by-side or stacked arrangements]
7/00 Constructional details common to different types of electric apparatus (casings, cabinets, drawers [H05K 5/00])

7/005 . . . Arrangements of circuit components without supporting structure
7/02 . Arrangements of circuit components or wiring on supporting structure
7/023 . . . Stackable modules
7/026 . . . Multiple connections subassemblies
7/04 . . . on conductive chassis
7/06 . . . on insulating boards (e.g. wiring harnesses [for printed circuits [H05K 1/18, H05K 3/30])
7/08 . . . on perforated boards
7/10 . . . Plug-in assemblages of components (e.g. IC sockets)
7/1007 . . . with means for increasing contact pressure at the end of engagement of coupling parts
7/1015 . . . having exterior leads
7/1023 . . . (co-operating by abutting, e.g. flat pack)
7/103 . . . (co-operating by sliding, e.g. DIP carriers)
7/1038 . . . [with spring contact pieces ([H05K 7/1046 takes precedence])
7/1046 . . . [J-shaped leads]
7/1053 . . . [having interior leads]
7/1061 . . . (co-operating by abutting)
7/1069 . . . [with spring contact pieces]
7/1076 . . . [co-operating by sliding]
7/1084 . . . [pin grid array package carriers]
7/1092 . . . [with built-in components, e.g. intelligent sockets]
7/12 . . . Resilient or clamping means for holding component to structure
7/14 . Mounting supporting structure in casing or on frame or rack ([H05K 7/18 takes precedence])
7/1401 . . . comprising clamping or extracting means ([H05K 7/10 takes precedence])
7/1402 . . . [for securing or extracting printed circuit boards]
7/1404 . . . [by edge clamping, e.g. wedges]
7/1405 . . . [by clips or resilient members, e.g. hooks]
7/1407 . . . [by turn-bolt or screw member]
7/1408 . . . [by a unique member which latches several boards, e.g. locking bars]
7/1409 . . . [by lever-type mechanisms]
7/1411 . . . [for securing or extracting box-type drawers]
7/1412 . . . [hold down mechanisms, e.g. avionic racks]
7/1414 . . . [with power interlock]
7/1415 . . . [manual gripping tools]
7/1417 . . . [having securing means for mounting boards, plates or wiring boards ([H05K 7/1461 takes precedence])
7/1418 . . . [Card guides, e.g. grooves ([H05K 7/1425 takes precedence])
7/142 . . . [Spacers not being card guides]
7/1421 . . . [Drawers for printed circuit boards]
7/1422 . . . [Printed circuit boards receptacles, e.g. stacked structures, electronic circuit modules or box like frames]
7/1424 . . . [Card cages]
7/1425 . . . [of standardised dimensions, e.g. 19"-subrack]
7/1427 . . . [Housings]
7/1428 . . . [for small modular apparatus with terminal block]
7/1429 . . . [for circuits carrying a CPU and adapted to receive expansion cards]
7/1431 . . . [Retention mechanisms for CPU modules]
7/1432 . . . [for power drive units]
7/1434 . . . [for electronics exposed to high gravitational force; Cylindrical housings]
7/1435 . . . [Expandable constructions]
7/1438 . . . [Back panels or connecting means therefor; Terminals; Coding means to avoid wrong insertion]
7/1439 . . . [Back panel mother boards]
7/1441 . . . [with a segmented structure]
7/1442 . . . [with a radial structure]
7/1444 . . . [Complex or three-dimensional-arrangements; Stepped or dual mother boards]
7/1445 . . . [with double-sided connections]
7/1447 . . . [External wirings; Wiring ducts; Laying cables]
7/1448 . . . [with connections to the front board]
7/1449 . . . [with connections to the back board]
7/1451 . . . [with connections between circuit boards or units]
7/1452 . . . [Mounting of connectors; Switching; Reinforcing of back panels]
on hinges or pivots
{ for racks or cabinets of standardized dimensions,
  heat-transfer, e.g. fins details, F28F 13/00
}

wherein heat is removed through air-to-liquid
{ Air circulating in closed loop within cabinets
} or
{ Forced ventilation of a gaseous coolant ( in
closed loop H05K 7/20754) }

{ within server blades for removing heat from
heat source }

{ within rooms for removing heat from
server blades }

{ Liquid coolant with phase change }

{ within server blades for removing heat from
heat source }

{ within cabinets for removing heat from
server blades }

{ Thermal management, e.g. server temperature
control }

{ for vehicle electronic casings }

{ Heat transfer by conduction from internal
heat source to heat radiating structure
( H05K 7/20863 takes precedence) }

{ Forced ventilation, e.g. on heat dissipators
coupled to components }

{ Liquid coolant without phase change }

{ within rooms for removing heat from
sub-boards }

{ Thermal management, e.g. inverter
temperature control }

{ for display panels }

{ Liquid coolant without phase change }

{ Liquid coolant with phase change }

{ Thermal management, e.g. inverter
temperature control }

{ for display panels }
[Heat transfer by conduction from internal heat source to heat radiating structure (H05K 7/20972 takes precedence)]

[Forced ventilation, e.g. on heat dissipaters coupled to components]

[Liquid coolant without phase change]

[Liquid coolant with phase change]

Screening of apparatus or components against electric or magnetic fields (devices for absorbing radiation from an antenna H01Q 17/00)

[Shielded walls, floors, ceilings, e.g. wallpaper, wall panel, electro-conductive plaster, concrete, cement, mortar]

[Shielded windows]

[Casings (standardised racks H05K 9/0062)]

[Rooms or chambers (anechoic chambers G01R 29/0821)]

[Shielded walls, floors, ceilings, e.g. wallpaper, wall panel, electro-conductive plaster, concrete, cement, mortar]

[Shielded windows]

[Casings (standardised racks H05K 9/0062)]

[Rooms or chambers (anechoic chambers G01R 29/0821)]

{Placing of components on belts holding the components in a predetermined order}

{Methods for measuring the shielding efficiency; Apparatus therefor; Isolation container for testing}

{Active shielding}

{Shielding materials (H05K 9/0003 takes precedence)}

{Magnetic shielding materials}

{comprising superconductors}

{Electrostatic discharge protection, e.g. ESD treated surface for rapid dissipation of charges}

{Electromagnetic shielding materials, e.g. EMI, RFI shielding (H05K 9/0002 takes precedence)}

{comprising electro-conductive non-fibrous particles embedded in an electrically insulating supporting structure, e.g. powder, flakes, whiskers (H05K 9/0086 takes precedence)}

{comprising a single continuous metallic layer on an electrically insulating supporting structure, e.g. metal foil, film, plating coating, electro-deposition, vapour-deposition}

{comprising a single discontinuous metallic layer on an electrically insulating supporting structure, e.g. metal grid, perforated metal foil, film, aggregated flakes, sintering}

{comprising a plurality of shielding layers; combining different shielding material structure}

{comprising electro-conductive fibres, e.g. metal fibres, carbon fibres, metallised textile fibres, electro-conductive mesh, woven, non-woven mat, fleece, cross-linked}

{comprising electro-conductive pigments, e.g. paint, ink, tampon printing}

{being light-transmitting, e.g. transparent, translucent}

{for television displays, e.g. plasma display panel}

{for shielding electrical cables}

Arrangements for improving the operating reliability of electronic equipment, e.g. by providing a similar standby unit

Combinations of a radio or television receiver with apparatus having a different main function (combined with clocks G04B 47/00; controlled by a clock G04C 21/28)

with vehicles

Apparatus or processes specially adapted for manufacturing or adjusting assemblages of electric components

[using handtools (for mounting on a circuit board H05K 13/0447)]

[Orientation; Alignment; Positioning]

[Placing of components on belts holding the terminals]

[placing the components in a predetermined order]
13/0053  { Arrangements for assisting the manual mounting of components, e.g. special tables or light spots indicating the place for mounting }
13/0061  { Tools for holding the circuit boards during processing; handling transport of printed circuit boards }
13/0069  { Holders for printed circuit boards }
13/0076  { Straightening or aligning terminal leads of pins mounted on boards, during transport of the boards }
13/0084  { Containers and magazines for components, e.g. tube-like magazines }
13/0092  { Treatment of the terminal leads as a separate operation (during transport H05K 13/0076, H05K 13/023; during mounting H05K 13/041) }
13/02  { Loading or unloading of containers (H05K 13/028 takes precedence) }
13/0215  { Interconnecting of containers, e.g. splicing of tapes }
13/022  { with orientation of the elements }
13/023  { with bending or straightening of the terminal leads }
13/024  { Straightening or aligning terminal leads }
13/025  { of components having oppositely extending terminal leads }
13/026  { of components having terminal leads in side by side relationship, e.g. using combing elements }
13/027  { Fluid transport of components }
13/028  { Simultaneously loading a plurality of loose objects, e.g. by means of vibrations, pressure differences, magnetic fields }
13/029  { Feeding axial lead components, e.g. using vibrating bowls, magnetic fields (H05K 13/022 takes precedence) }
13/04  { Mounting of components, e.g. leadless components }
13/0404  { Pick-and-place heads or apparatus, e.g. with jaws }

**WARNING**

Group H05K 13/0404 is impacted by reclassification into groups H05K 13/0406, H05K 13/0408, H05K 13/041, H05K 13/0411 and H05K 13/0413.
All groups listed in this Warning should be considered in order to perform a complete search.

13/0406  { Drive mechanisms for pick-and-place heads, e.g. details relating to power transmission, motors or vibration damping }

**WARNING**

Group H05K 13/0406 is incomplete pending reclassification of documents from groups H05K 13/0404, H05K 13/0413 and H05K 13/0452.
All groups listed in this Warning should be considered in order to perform a complete search.

13/0408  { Incorporating a pick-up tool }

**WARNING**

Group H05K 13/0408 is incomplete pending reclassification of documents from group H05K 13/0404. Group H05K 13/0408 is also impacted by reclassification into group H05K 13/0409.
Groups H05K 13/0404, H05K 13/0408 and H05K 13/0409 should be considered in order to perform a complete search.

13/0409  { Sucking devices }

**WARNING**

Group H05K 13/0409 is incomplete pending reclassification of documents from group H05K 13/0408. Group H05K 13/0409 is also impacted by reclassification into group H05K 13/0408.
Groups H05K 13/0408 and H05K 13/0409 should be considered in order to perform a complete search.

13/041  { Having multiple pick-up tools }

**WARNING**

Group H05K 13/041 is incomplete pending reclassification of documents from groups H05K 13/0404, H05K 13/0413 and H05K 13/0452.
All groups listed in this Warning should be considered in order to perform a complete search.
[having multiple mounting heads]

**WARNING**

Group H05K 13/0411 is incomplete pending reclassification of documents from groups H05K 13/0404 and H05K 13/0452.

Groups H05K 13/0404, H05K 13/0452 and H05K 13/0411 should be considered in order to perform a complete search.

[with orientation of the component while holding it; Drive mechanisms for gripping tools, e.g. lifting, lowering or turning of gripping tools]

**WARNING**

Group H05K 13/0413 is incomplete pending reclassification of documents from groups H05K 13/0404 and H05K 13/0452.

Groups H05K 13/0404, H05K 13/0452 and H05K 13/0413 should be considered in order to perform a complete search.

[Feeding with belts or tapes]

**WARNING**

Group H05K 13/0417 is impacted by reclassification into group H05K 13/0419.

Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

[tape feeders]

**WARNING**

Group H05K 13/0419 is incomplete pending reclassification of documents from groups H05K 13/0404 and H05K 13/0417.

Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

[with treatment of the terminal leads]

**WARNING**

Group H05K 13/0421 is impacted by reclassification into group H05K 13/0417.

Groups H05K 13/0417 and H05K 13/0419 should be considered in order to perform a complete search.

[for components being oppositely extending terminal leads (H05K 13/0421 takes precedence)]

[Feeding one by one by other means than belts]

[with containers]

[incorporating means for treating the terminal leads only before insertion]

[incorporating means for treating the terminal leads before and after insertion or only after insertion]

[Hand tools therefor]

[Mounting machines or lines comprising a plurality of tools for guiding different components to the same mounting place (H05K 13/0406, H05K 13/0411 take precedence)]

**WARNING**

Group H05K 13/0452 is impacted by reclassification into groups H05K 13/0406, H05K 13/0411, H05K 13/0413 and H05K 13/0417.

All groups listed in this Warning should be considered in order to perform a complete search.

[simultaneously punching the circuit board]

[Surface mounting (surface mounted components H05K 3/341)]

[by soldering (H05K 13/0469 takes precedence)]

[by applying a glue or viscous material]

[Cutting and clinching the terminal ends of the leads after they are fitted on a circuit board]

[Simultaneously mounting of different components]

[using templates; using magazines, the configuration of which corresponds to the sites on the boards where the components have to be attached]

[Replacement and removal of components]

[Hand tools therefor]

[having a plurality of work-stations]

.Wiring by machine

.Accessories therefor, e.g. light spots

.Monitoring manufacture of assemblages

**WARNING**

Group H05K 13/08 is impacted by reclassification into groups H05K 13/081, H05K 13/0812, H05K 13/0813, H05K 13/0815, H05K 13/0817, H05K 13/0818, H05K 13/082, H05K 13/083, H05K 13/084, H05K 13/085, H05K 13/0853, H05K 13/0857, H05K 13/086, H05K 13/087, H05K 13/0882, H05K 13/0885, H05K 13/0888, H05K 13/0889 and H05K 13/0895.

All groups listed in this Warning should be considered in order to perform a complete search.

[Integration of optical monitoring devices in assembly lines; Processes using optical monitoring devices specially adapted for controlling devices or machines in assembly lines]

**WARNING**

Group H05K 13/081 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/081 should be considered in order to perform a complete search.
13/0812 . . . [the monitoring devices being integrated in the mounting machine, e.g. for monitoring components, leads, component placement]

**WARNING**

Group H05K 13/0812 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0812 should be considered in order to perform a complete search.

13/0813 . . . [Controlling of single components prior to mounting, e.g. orientation, component geometry (H05K 13/0812 takes precedence)]

**WARNING**

Group H05K 13/0813 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0813 should be considered in order to perform a complete search.

13/0815 . . . [Controlling of component placement on the substrate during or after manufacturing]

**WARNING**

Group H05K 13/0815 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0815 should be considered in order to perform a complete search.

13/0817 . . . [Monitoring of soldering processes (inspection of solder joints or of printed solder paste G01N 21/9568)]

**WARNING**

Group H05K 13/0817 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0817 should be considered in order to perform a complete search.

13/0818 . . . [Setup of monitoring devices prior to starting mounting operations; Teaching of monitoring devices for specific products; Compensation of drifts during operation, e.g. due to temperature shifts]

**WARNING**

Group H05K 13/0818 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0818 should be considered in order to perform a complete search.

13/082 . . . [Integration of non-optical monitoring devices, i.e. using non-optical inspection means, e.g. electrical means, mechanical means or X-rays]

**WARNING**

Group H05K 13/082 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/082 should be considered in order to perform a complete search.

13/083 . . . [Quality monitoring using results from monitoring devices, e.g. feedback loops (H05K 13/084 takes precedence)]

**WARNING**

Group H05K 13/083 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/083 should be considered in order to perform a complete search.

13/084 . . . [Product tracking, e.g. of substrates during the manufacturing process; Component traceability]

**WARNING**

Group H05K 13/084 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/084 should be considered in order to perform a complete search.

13/085 . . . [Production planning, e.g. of allocation of products to machines, of mounting sequences at machine or facility level]

**WARNING**

Group H05K 13/085 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/085 should be considered in order to perform a complete search.

13/0853 . . . [Determination of transport trajectories inside mounting machines]

**WARNING**

Group H05K 13/0853 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0853 should be considered in order to perform a complete search.
13/0857 . . . [Product-specific machine setup; Changeover of machines or assembly lines to new product type]

**WARNING**

Group H05K 13/0857 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0857 should be considered in order to perform a complete search.

13/086 . . . [Supply management, e.g. supply of components or of substrates]

**WARNING**

Group H05K 13/086 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/086 should be considered in order to perform a complete search.

13/087 . . . [Equipment tracking or labelling, e.g. tracking of nozzles, feeders or mounting heads]

**WARNING**

Group H05K 13/087 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/087 should be considered in order to perform a complete search.

13/0882 . . . [Control systems for mounting machines or assembly lines, e.g. centralized control, remote links, programming of apparatus and processes as such (H05K 13/083 takes precedence)]

**WARNING**

Group H05K 13/0882 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0882 should be considered in order to perform a complete search.

13/0885 . . . [Power supply]

**WARNING**

Group H05K 13/0885 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0885 should be considered in order to perform a complete search.

13/0888 . . . [Ergonomics; Operator safety; Training; Failsafe systems]

**WARNING**

Group H05K 13/0888 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0888 should be considered in order to perform a complete search.

13/089 . . . [Calibration, teaching or correction of mechanical systems, e.g. of the mounting head]

**WARNING**

Group H05K 13/089 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/089 should be considered in order to perform a complete search.

13/0895 . . . [Maintenance systems or processes, e.g. indicating need for maintenance]

**WARNING**

Group H05K 13/0895 is incomplete pending reclassification of documents from group H05K 13/08.

Groups H05K 13/08 and H05K 13/0895 should be considered in order to perform a complete search.

2201/00 Indexing scheme relating to printed circuits covered by H05K 1/00

2201/01 . . . Dielectrics

2201/0104 . . . Properties and characteristics in general

2201/0108 . . . Transparent

2201/0112 . . . Absorbing light, e.g. dielectric layer with carbon filler for laser processing

2201/0116 . . . Porous, e.g. foam

2201/0112 . . . Flame-retardant; Preventing of inflammation

2201/0125 . . . Shrinkable, e.g. heat-shrinkable polymer

2201/0129 . . . Thermoplastic polymer, e.g. auto-adhesive layer; Shaping of thermoplastic polymer

2201/0133 . . . Elastomeric or compliant polymer (elastomeric conductor H05K 2201/0314)

2201/0137 . . . Materials

2201/0141 . . . Liquid crystal polymer [LCP]

2201/0145 . . . Polyester, e.g. polyethylene terephthalate [PET], polyethylene naphthalate [PEN]

2201/015 . . . Fluoropolymer, e.g. polytetrafluoroethylene [PTFE]

2201/0154 . . . Polyimide

2201/0158 . . . Polyalkene or polyolefin, e.g. polyethylene [PE], polypropylene [PP]

2201/0162 . . . Silicon containing polymer, e.g. silicone

2201/0166 . . . Polymeric layer used for special processing, e.g. resist for etching insulating material or photosist used as a mask during plasma etching

2201/017 . . . Glass ceramic coating, e.g. formed on inorganic substrate (inorganic, non-metallic substrates H05K 1/0306)
Fibers and reinforcement materials

Fillers and particles

Dielectric layers

Unidirectional or parallel fibers

Conductive fibers

Paper, e.g. as reinforcement (paper sheet substrates H05K 1/0386)

Unidirectional or parallel fibers

Woven fibrous reinforcement or textile (textile substrates H05K 1/038)

Non-woven fibrous reinforcement

Fibers with a special cross-section, e.g. elliptical

Conductive materials

Properties and characteristics in general

Solder used for other purposes than connections between PCB or components, e.g. for filling vias or for programmable patterns

Shape memory alloy (SMA)

Metallic part with specific elastic properties, e.g. bent piece of metal as electrical contact

Elastomeric connector or conductor, e.g. rubber with metallic filler (elastomeric dielectric H05K 2201/0133)

Thin film conductor layer; Thin film passive component

Materials

Carbon

Inorganic, non-metallic conductor, e.g. indium-tin oxide (ITO)

Intrinsic semiconductor polymer (ICP); Semiconductive polymer

Structure of the conductor

Layered conductors or foils

Layered conductor, e.g. layered metal substrate, layered finish layer, layered thin film adhesion layer (etched tri-metal structure H05K 2201/0361)

Intermediate metal, e.g. before reinforcing of conductors by plating

Electroless sublayer, e.g. Ni, Co, Cd or Ag; Transferred electroless sublayer

Overplating, e.g. for reinforcing conductors or bumps; Plating over filled vias (reinforcing the conductive pattern H05K 3/24)

Paste overlayer, i.e. conductive paste or solder paste over conductive layer

Differences between the conductors of different layers of a multilayer

Metal foils

Resin coated copper (RCC)

Etched tri-metal structure, i.e. metal layers or metal patterns on both sides of a different central metal layer which is later at least partly etched

Conductor shape

Metallic bump or raised conductor not used as solder bump (solder materials or compositions and methods of application thereof H05K 3/3457)

Hollow conductors, i.e. conductors partially or completely surrounding a void, e.g. hollow waveguides

Conductors having a fine structure, e.g. providing a plurality of contact points with a structured tool (providing micro- or nanometer scale roughness on a metal surface H05K 2203/0307)

Flush conductors, i.e. flush with the surface of the printed circuit

Stacked conductors
2201/0382 . . . Continuously deformed conductors
2201/0385 . . . Displaced conductors
2201/0388 . . . Other aspects of conductors
2201/0391 . . . Using different types of conductors
2201/0394 . . . Conductor crossing over a hole in the substrate
2201/0397 . . . Tab (forming integral conductive tabs H05K 3/4092)
2201/04 . . . Assemblies of printed circuits
2201/041 . . . Stacked PCBs, i.e. having neither an empty space nor mounted components in between
2201/042 . . . Stacked spaced PCBs; Planar parts of folded flexible circuits having mounted components in between or spaced from each other
2201/043 . . . Stacked PCBs with their backs attached to each other without electrical connection
2201/044 . . . Details of backplane or midplane for mounting orthogonal PCBs
2201/045 . . . Hierarchy auxiliary PCB, i.e. more than two levels of hierarchy for daughter PCBs are important
2201/046 . . . Planar parts of folded PCBs making an angle relative to each other (assembling printed circuits perpendicular to each other H05K 3/366)
2201/047 . . . Box-like arrangements of PCBs
2201/048 . . . Second PCB mounted on first PCB by inserting in window or holes of the first PCB
2201/049 . . . PCB for one component, e.g. for mounting onto mother PCB
2201/05 . . . Flexible printed circuits [FPCs]
2201/051 . . . Rolled
2201/052 . . . Branched
2201/053 . . . Tails
2201/055 . . . Folded back on itself
2201/056 . . . Folded around rigid support or component
2201/057 . . . Shape retainable
2201/058 . . . Direct connection between two or more FPCs or between flexible parts of rigid PCBs
2201/06 . . . Thermal details
2201/062 . . . Means for thermal insulation, e.g. for protection of parts
2201/064 . . . Fluid cooling, e.g. by integral pipes
2201/066 . . . Heat sink mounted on the surface of the PCB (heat sink inserted in the PCB H05K 2201/10416)
2201/068 . . . wherein the coefficient of thermal expansion is important
2201/07 . . . Electric details
2201/070 . . . Shielding
2201/0715 . . . provided by an outer layer of PCB
2201/0723 . . . provided by an inner layer of PCB
2201/073 . . . High voltage adaptations (overvoltage protection H05K 1/0257)
2201/0738 . . . Use of voltage responsive materials, e.g. voltage switchable dielectric or varistor materials
2201/0746 . . . Protection against transients, e.g. layout adapted for plugging of connector
2201/0753 . . . Insulation
2201/0761 . . . Insulation resistance, e.g. of the surface of the PCB between the conductors
2201/0769 . . . Anti metal-migration, e.g. avoiding tin whisker growth
2201/0776 . . . Resistance and impedance
2201/0784 . . . Uniform resistance, i.e. equalizing the resistance of a number of conductors
2201/0792 . . . Means against parasitic impedance; Means against eddy currents
2201/08 . . . Magnetic details
2201/083 . . . Magnetic materials
2201/086 . . . for inductive purposes, e.g. printed inductor with ferrite core
2201/09 . . . Shape and layout
2201/09009 . . . Substrate related
2201/09018 . . . Rigid curved substrate
2201/09027 . . . Non-rectangular flat PCB, e.g. circular
2201/09036 . . . Recesses or grooves in insulating substrate (recess in metallic substrate H05K 2201/09745)
2201/09045 . . . Locally raised area or protrusion of insulating substrate (rigid curved substrate H05K 2201/09918)
2201/09054 . . . Raised area or protrusion of metal substrate
2201/09063 . . . Holes or slots in insulating substrate not used for electrical connections
2201/09072 . . . Hole or recess under component or special relationship between hole and component
2201/09081 . . . Tongue or tail integrated in planar structure, e.g. obtained by cutting from the planar structure
2201/0909 . . . Preformed cutting or breaking line
2201/091 . . . Locally and permanently deformed areas including dielectric material
2201/09109 . . . Locally detached layers, e.g. in multilayer PCBs
2201/09118 . . . Moulded substrate
2201/09127 . . . PCB or component having an integral separable or breakable part
2201/09136 . . . Means for correcting warpage
2201/09145 . . . Edge details
2201/09154 . . . Bevelled, chamfered or tapered edge
2201/09163 . . . Slotted edge
2201/09172 . . . Notches between edge pads
2201/09181 . . . Notches in edge pads
2201/0919 . . . Exposing inner circuit layers or metal planes at the side edge of the PCB or at the walls of large holes (shielding provided by an inner layer of PCB H05K 2201/0723)
2201/092 . . . Exposing inner circuit layers or metal planes at the walls of high aspect ratio holes (forming plated-through holes H05K 3/42; cutting around hole H05K 2203/0242)
2201/09209 . . . Shape and layout details of conductors
2201/09218 . . . Conductive traces
2201/09227 . . . Layout details of a plurality of traces, e.g. escape layout for Ball Grid Array [BGA] mounting
2201/09236 . . . Parallel layout (layout of balanced signal pairs H05K 1/0245; superposed layout H05K 2201/09672)
2201/09245 . . . Crossing layout (alternating conductors H05K 2201/097)
2201/09254 . . . Branched layout
2201/09263 . . . Meander
2201/09272 . . . Layout details of angles or corners
2201/09281 . . . Layout details of a single conductor (meander H05K 2201/0926; layout details of angles or corners H05K 2201/09272)
2201/0929 . . . Conductive planes
2201/093 . . . Layout of power planes, ground planes or power supply conductors, e.g. having special clearance holes therein (reduction of cross-talk, noise or interference by patterned shielding planes, ground planes or power planes H05K 1/0224)

2201/09309 . . . Core having two or more power planes; Capacitive laminate of two power planes

2201/09318 . . . Core having one signal plane and one power plane

2201/09327 . . . Special sequence of power, ground and signal layers in multilayer PCB

2201/09336 . . . Signal conductors in same plane as power plane

2201/09345 . . . Power and ground in the same plane; Power planes for two voltages in one plane

2201/09354 . . . Ground conductor along edge of main surface (edge contacts H05K 3/403) wherein only contours around conductors are removed for insulation

2201/09372 . . . Pads and lands

2201/09381 . . . Shape of non-curved single flat metallic pad, land or exposed part thereof; Shape of electrode of leadless component (notches in edge pads H05K 2201/09181)

2201/0939 . . . Curved pads, e.g. semi-circular or elliptical pads or lands

2201/094 . . . Array of pads or lands differing from one another, e.g. in size, pitch, thickness; Using different connections on the pads (using different types of conductors H05K 2201/09391)

2201/09409 . . . Multiple rows of pads, lands, terminals or dummy patterns; Multiple rows of mounted components

2201/09418 . . . Special orientation of pads, lands or terminals of component, e.g. radial or polygonal orientation

2201/09427 . . . Special relation between the location or dimension of a pad or land and the location or dimension of a terminal

2201/09436 . . . Pads or lands on permanent coating which covers the other conductors

2201/09445 . . . Pads for connections not located at the edge of the PCB, e.g. for flexible circuits

2201/0945 . . . Inner lands, i.e. lands around via or plated through-hole in internal layer of multilayer PCB

2201/09463 . . . Partial lands, i.e. lands or conductive rings not completely surrounding the hole (landless plated-through hole or via H05K 2201/09545)

2201/09472 . . . Recessed pad for surface mounting (recess in pad H05K 2201/09745); Recessed electrode of component

2201/09481 . . . Via in pad; Pad over filled via (if used for surface mounting H05K 1/113)

2201/0949 . . . Pad close to a hole, not surrounding the hole (if used for surface mounting H05K 1/114)

2201/095 . . . Conductive through-holes or vias

2201/09509 . . . Blind vias, i.e. vias having one side closed

2201/09518 . . . Deep blind vias, i.e. blind vias connecting the surface circuit to circuit layers deeper than the first buried circuit layer

2201/09527 . . . Inverse blind vias, i.e. bottoms outwards in multilayer PCB; Blind vias in centre of PCB having opposite bottoms

2201/09536 . . . Buried plated-through-holes, i.e. plated through-holes formed in a core before lamination

2201/09545 . . . Plated through-holes or blind vias without lands

2201/09554 . . . Via connected to metal substrate

2201/09563 . . . Metal filled via (plated through-hole filled with insulating material H05K 2201/0959)

2201/09572 . . . Solder filled plated-through-hole in the final product (soldering lead-in-hole components H05K 3/3447)

2201/09581 . . . Applying an insulating coating on the walls of holes

2201/0959 . . . Plated through-holes or plated blind vias filled with insulating material

2201/096 . . . Vertically aligned vias, holes or stacked vias

2201/09609 . . . Via grid, i.e. two-dimensional array of vias or holes in a single plane (interposers H05K 2201/10378)

2201/09618 . . . Via fence, i.e. one-dimensional array of vias

2201/09627 . . . Special connections between adjacent vias, not for grounding vias (redundant conductors or connections H05K 2201/0979)

2201/09636 . . . Details of adjacent, not connected vias

2201/09645 . . . Patterning on via walls; Plural lands around one hole

2201/09654 . . . covering at least two types of conductors provided for in H05K 2201/09218 - H05K 2201/095

2201/09663 . . . Divided layout, i.e. conductors divided in two or more parts (branched layout H05K 2201/09254)

2201/09672 . . . Superposed layout, i.e. in different planes (parallel traces in one plane H05K 2201/09236)

2201/09681 . . . Mesh conductors, e.g. as a ground plane

2201/0969 . . . Apertured conductors

2201/097 . . . Alternating conductors, e.g. alternating different shaped pads, twisted pairs; Alternating components

2201/09709 . . . Staggered pads, lands or terminals; Parallel conductors in different planes

2201/09718 . . . Clearance holes

2201/09727 . . . Varying width along a single conductor; Conductors or pads having different widths

2201/09736 . . . Varying thickness of a single conductor; Conductors in the same plane having different thicknesses

2201/09745 . . . Recess in conductor, e.g. in pad or in metallic substrate

2201/09754 . . . Connector integrally incorporated in the PCB or in housing (mounted connector H05K 2201/10189)

2201/09763 . . . Printed component having superposed conductors, but integrated in one circuit layer

2201/09772 . . . Conductors directly under a component but not electrically connected to the component (cooling of mounted components by printed thermal vias H05K 1/0206)
other objects, e.g. metallic pieces

2201/09836...Oblique hole, via or bump
2201/09845...Stepped hole, via, edge, bump or conductor
2201/09854...Hole or via having special cross-section, e.g. elliptical
2201/09863...Concave hole or via
2201/09872...Insulating conformal coating (foil encapsulation H05K 2203/1311)
2201/09881...Coating only between conductors, i.e. flush with the conductors
2201/0989...Coating free areas, e.g. areas other than pads or lands free of solder resist
2201/099...Coating over pads, e.g. solder resist partly over pads
2201/09909...Special local insulating pattern, e.g. as dam around component
2201/09918...Optically detected marks used for aligning tool relative to the PCB, e.g. for mounting of components
2201/09927...Machine readable code, e.g. bar code
2201/09936...Marks, inscriptions, etc. for information
2201/09945...Universal aspects, e.g. universal inner layers or via grid, or anisotropic interposer
2201/09954...More mounting possibilities, e.g. on same place of PCB, or by using different sets of edge pads
2201/09963...Programming circuit by using small elements, e.g. small PCBs
2201/09972...Partitioned, e.g. portions of a PCB dedicated to different functions; Boundary lines therefore; Portions of a PCB being processed separately or differently
2201/09981...Metallised walls
2201/0999...Circuit printed on or in housing, e.g. housing as PCB; Circuit printed on the case of a component; PCB affixed to housing
2201/10...Details of components or other objects attached to or integrated in a printed circuit board
2201/10007...Types of components
2201/10015...Non-printed capacitor
2201/10022...Non-printed resistor
2201/1003...Non-printed inductor
2201/10037...Printed or non-printed battery
2201/10045...Mounted network component having plural terminals
2201/10053...Switch
2201/1006...Non-printed filter
2201/10068...Non-printed resonator
2201/10075...Non-printed oscillator
2201/10083...Electromechanical or electro-acoustic component, e.g. microphone
2201/1009...Electromotor
2201/10098...Component for radio transmission, e.g. Radio Frequency Identification Tag [RFID]
2201/10106...Light emitting diode [LED]
2201/10113...Lamp
2201/10121...Optical component, e.g. opto-electronic component
2201/10128...Display
2201/10136...Liquid Crystal display [LCD]
2201/10143...Solar cell
2201/10151...Sensor
2201/10159...Memory
2201/10166...Transistor
2201/10174...Diode
2201/10181...Fuse
2201/10189...Non-printed connector
2201/10196...Variable component, e.g. variable resistor
2201/10204...Dummy component, dummy PCB or template, e.g. for monitoring, controlling of processes, comparing, scanning
2201/10212...Programmable component
2201/10219...Thermolectric component
2201/10227...Other objects, e.g. metallic pieces
2201/10234...Metallic balls (solder balls H05K 2203/041)
2201/10242...Metallic cylinders (small solder preforms other than balls H05K 2203/0415)
2201/1025...Metallic discs (small solder preforms other than balls H05K 2203/0415)
2201/10257...Hollow pieces of metal, e.g. used in connection between component and PCB
2201/10265...Metallic coils or springs, e.g. as part of a connection element
2201/10272...Busbars, i.e. thick metal bars mounted on the PCB as high-current conductors (metal strips H05K 2201/1028)
2201/1028...Thin metal strips as connectors or conductors
2201/10287...Metal wires as connectors or conductors
2201/10295...Metallic connector elements partly mounted in a hole of the PCB
2201/10303...Pin-in-hole mounted pins
2201/1031...Surface mounted metallic connector elements
2201/10318...Surface mounted metallic pins
2201/10325...Sockets, i.e. female type connectors comprising metallic connector elements integrated in, or bonded to a common dielectric support
2201/10333...Individual female type metallic connector elements
2201/1034...Edge terminals, i.e. separate pieces of metal attached to the edge of the PCB (tab H05K 2201/0397)
2201/10348...Fuzz's as connector elements, i.e. small pieces of metallic fiber to make connection
2201/10356...Cables
2201/10363...Jumpers, i.e. non-printed cross-over connections
2201/10371...Shields or metal cases
2201/10378...Interposers
2201/10386...Clip leads; Terminals gripping the edge of a substrate
2201/10393 . . . Clamping a component by an element or a set of elements
2201/10401 . . . Eyelets, i.e. rings inserted into a hole through a circuit board
2201/10409 . . . Screws
2201/10416 . . . Metallic blocks or heatsinks completely inserted in a PCB (metallic supports H05K 3/0061)
2201/10424 . . . Frame holders
2201/10431 . . . Details of mounted components (printed components H05K 1/16)
2201/10439 . . . Position of a single component
2201/10446 . . . Mounted on an edge (soldering edge mounted components H05K 3/3403; edge terminals H05K 2201/1034)
2201/10454 . . . Vertically mounted
2201/10462 . . . Flat component oriented parallel to the PCB surface
2201/10469 . . . Asymmetrically mounted component
2201/10477 . . . Inverted
2201/10484 . . . Obliquely mounted
2201/10492 . . . Electrically connected to another device (mounted components directly electrically connected to each other H05K 2201/1053)
2201/105 . . . Mechanically attached to another device (attached components H05K 2201/10537)
2201/10507 . . . Involving several components
2201/10515 . . . Stacked components
2201/10522 . . . Adjacent components
2201/1053 . . . Mounted components directly electrically connected to each other, i.e. not via the PCB
2201/10537 . . . Attached components
2201/10545 . . . Related components mounted on both sides of the PCB
2201/10553 . . . Component over metal, i.e. metal plate in between bottom of component and surface of PCB
2201/1056 . . . Metal over component, i.e. metal plate over component mounted on or embedded in PCB
2201/10568 . . . Integral adaptations of a component or an auxiliary PCB for mounting, e.g. integral spacer element
2201/10575 . . . Insulating foil under component (permanent spacer or stand-off H05K 2201/2036)
2201/10583 . . . Cylindrically shaped component; Fixing means therefore
2201/1059 . . . Connections made by press-fit insertion
2201/10598 . . . Means for fastening a component, a casing or a heat sink whereby a pressure is exerted on the component towards the PCB
2201/10606 . . . Permanent holder for component or auxiliary PCB mounted on a PCB (clamping a component by an element or a set of elements H05K 2201/10393)
2201/10613 . . . Details of electrical connections of non-printed components, e.g. special leads
2201/10621 . . . Components characterised by their electrical contacts
2201/10628 . . . Leaded surface mounted device (soldering surface mounted leaded components H05K 3/3421)
2201/10636 . . . Leadless chip, e.g. chip capacitor or resistor
2201/10645 . . . Disc shaped leadless component
2201/10651 . . . Component having two leads, e.g. resistor, capacitor
2201/10659 . . . Different types of terminals for the same component, e.g. solder balls combined with leads
2201/10666 . . . Plated through-hole for surface mounting on PCB
2201/10674 . . . Flip chip
2201/10681 . . . Tape Carrier Package [TCP]; Flexible sheet connector
2201/10689 . . . Leaded Integrated Circuit [IC] package, e.g. dual-in-line [DIL]
2201/10704 . . . Pin grid array [PGA]
2201/10712 . . . Via grid array, e.g. via grid array capacitor
2201/10719 . . . Land grid array [LGA]
2201/10727 . . . Leadless chip carrier [LCC], e.g. chip-modules for cards
2201/10734 . . . Ball grid array [BGA]; Bump grid array
2201/10742 . . . Details of leads
2201/1075 . . . Shape details
2201/10757 . . . Bent leads
2201/10765 . . . Leads folded back, i.e. bent with an angle of 180 deg
2201/10772 . . . Leads of a surface mounted component bent for providing a gap between the lead and the pad during soldering
2201/1078 . . . Leads having locally deformed portion, e.g. for retention
2201/10787 . . . Leads having protrusions, e.g. for retention or insert stop
2201/10795 . . . Details of lead tips, e.g. pointed
2201/10803 . . . Tapered leads, i.e. leads having changing width or diameter
2201/1081 . . . Special cross-section of a lead; Different cross-sections of different leads; Matching cross-section, e.g. matched to a land
2201/10818 . . . Flat leads
2201/10825 . . . Distorted or twisted flat leads, i.e. deformed by torque
2201/10833 . . . having a curved or folded cross-section
2201/1084 . . . Notched leads
2201/10848 . . . Thinned leads
2201/10856 . . . Divided leads, e.g. by slot in length direction of lead, or by branching of the lead
2201/10863 . . . Adaptations of leads or holes for facilitating insertion
2201/10871 . . . Leads having an integral insert stop
2201/10878 . . . Means for retention of a lead in a hole
2201/10886 . . . Other details
2201/10893 . . . Grouped leads, i.e. element comprising multiple leads distributed around but not through a common insulator
2201/10901 . . . Lead partly inserted in hole or via
2201/10909 . . . Materials of terminal, e.g. of leads or electrodes of components
2201/10916 . . . Terminals having auxiliary metallic piece, e.g. for soldering
2201/10924 . . . Leads formed from a punched metal foil (affixing a prefabricated self-supporting metal foil pattern H05K 3/202)
H05K

2201/10931 . . . Exposed leads, i.e. encapsulation of component partly removed for exposing a part of lead, e.g. for soldering purposes
2201/10939 . . . Lead of component used as a connector
2201/10946 . . . Leads attached onto leadless component after manufacturing the component
2201/10954 . . . Other details of electrical connections
2201/10962 . . . Component not directly connected to the PCB
2201/10969 . . . Metallic case or integral heatsink of component electrically connected to a pad on PCB
2201/10977 . . . Encapsulated connections (applying non-metallic protective coatings for encapsulating mounted components H05K 3/284)
2201/10984 . . . Component carrying a connection agent, e.g. solder, adhesive (soldering leadless components having an array of bottom contacts H05K 3/3436; BGA components H05K 2201/10734)
2201/10992 . . . Using different connection materials, e.g. different solders, for the same connection

2201/20 Details of printed circuits not provided for in H05K 2201/01 - H05K 2201/10
2201/209 . . . Reinforced areas, e.g. for a specific part of a flexible printed circuit
2201/2018 . . . Presence of a frame in a printed circuit or printed circuit assembly
2201/2027 . . . Guiding means, e.g. for guiding flexible circuits
2201/2036 . . . Permanent spacer or stand-off in a printed circuit or printed circuit assembly (pattern for applying drops or paste H05K 2203/0545)
2201/2045 . . . Protection against vibrations
2201/2054 . . . Light-reflecting surface, e.g. conductors, substrates, coatings, dielectrics
2201/2063 . . . mixed adhesion layer containing metallic/ inorganic and polymeric materials
2201/2072 . . . Anchoring, i.e. one structure gripping into another (providing micro- or nanometer scale roughness on a metal surface H05K 2203/0307)
2201/2081 . . . Compound repelling a metal, e.g. solder
2201/209 . . . Auto-mechanical connection between a component and a PCB or between two PCBs

2203/00 Indexing scheme relating to apparatus or processes for manufacturing printed circuits covered by H05K 3/00
2203/01 . . . Tools for processing; Objects used during processing
2203/0104 . . . for patterning or coating
2203/0108 . . . Male die used for patterning, punching or transferring
2203/0113 . . . Female die used for patterning or transferring, e.g. temporary substrate having recessed pattern
2203/0117 . . . Pattern shaped electrode used for patterning, e.g. plating or etching
2203/0121 . . . Patterning, e.g. plating or etching by moving electrode
2203/0126 . . . Dispenser, e.g. for solder paste, for supplying conductive paste for screen printing or for filling holes
2203/013 . . . Inkjet printing, e.g. for printing insulating material or resist (using ink-jet printing to form a conductive pattern H05K 3/125)
2203/0134 . . . Drum, e.g. rotary drum or dispenser with a plurality of openings
2203/0139 . . . Blade or squeegee, e.g. for screen printing or filling of holes
2203/0143 . . . Using a roller; Specific shape thereof; Providing locally adhesive portions thereon
2203/0147 . . . Carriers and holders
2203/0152 . . . Temporary metallic carrier, e.g. for transferring material (affixing a prefabricated conductor pattern formed by electroplating or electroforming on a metallic carrier H05K 3/205)
2203/0156 . . . Temporary polymeric carrier or foil, e.g. for processing or transferring
2203/016 . . . Temporary inorganic, non-metallic carrier, e.g. for processing or transferring
2203/0165 . . . Holder for holding a Printed Circuit Board [PCB] during processing, e.g. during screen printing
2203/0169 . . . Using a temporary frame during processing
2203/0173 . . . Template for holding a PCB having mounted components thereon
2203/0178 . . . Projectile, e.g. for perforating substrate
2203/0182 . . . Using a temporary spacer element or stand-off during processing
2203/0186 . . . Mask formed or laid on PCB, the mask having recesses or openings specially designed for mounting components or body parts thereof
2203/0191 . . . Using tape or non-metallic foil in a process, e.g. during filling of a hole with conductive paste
2203/0195 . . . Tool for a process not provided for in H05K 3/00, e.g. tool for handling objects using suction, for deforming objects, for applying local pressure
2203/02 . . . Details related to mechanical or acoustic processing, e.g. drilling, punching, cutting, using ultrasound
2203/0207 . . . Partly drilling through substrate until a controlled depth, e.g. with end-point detection
2203/0214 . . . Back-up or entry material, e.g. for mechanical drilling
2203/0221 . . . Perforating
2203/0228 . . . Cutting, sawing, milling or shearing
2203/0235 . . . Laminating followed by cutting or slicing perpendicular to plane of the laminate; Embedding wires in an object and cutting or slicing the object perpendicular to direction of the wires
2203/0242 . . . Cutting around hole, e.g. for disconnecting land or Plated Through-Hole [PTH] or for partly removing a PTH
2203/025 . . . Abrading, e.g. grinding or sand blasting (deburring, rounding, bevelling or smoothing conductor edges H05K 2203/0346)
2203/0257 . . . Brushing, e.g. cleaning the conductive pattern by brushing or wiping
2203/0264 . . . Peeling insulating layer, e.g. foil, or separating mask
2203/0271 . . . Mechanical force other than pressure, e.g. shearing or pulling
2203/0278 . . . Flat pressure, e.g. for connecting terminals with anisotropic conductive adhesive
2203/0285 . . . Using ultrasound, e.g. for cleaning, soldering or wet treatment
2203/0292 . . . Using vibration, e.g. during soldering or screen printing
Metal processing

Providing micro- or nanometer scale roughness on a metal surface, e.g. by plating of nodules or dendrites

Oxidising metal

Working metal substrate or core, e.g. by etching, deforming

Punching metal foil, e.g. solder foil

Transferring metal or conductive material other than a circuit pattern, e.g. bump, solder, printed component

Deburring, rounding, bevelling or smoothing conductor edges

Making conductive layer thin, e.g. by etching

Stripping a part of an upper metal layer to expose a lower metal layer, e.g. by etching or using a laser

Etching selective parts of a metal substrate through part of its thickness, e.g. using etch resist

Etching temporary metallic carrier substrate

Etch stop layer, i.e. a buried barrier layer for preventing etching of layers under the etch stop layer

Pretreatment of metal, e.g. before finish plating, etching (improvement of the adhesion between an insulating substrate and a metal by special treatment of the metal)

Soldering or other types of metallurgical bonding (using molten metal)

Solder foil, tape or wire

Solder preforms in the shape of solder balls (soldering leadless components having an array of bottom contacts)

Small preforms other than balls, e.g. discs, cylinders or pillars

Remote solder depot on the PCB, the solder flowing to the connections from this depot

Solder powder or solder coated metal powder

Rerflowing of solder coated conductors, not during connection of components, e.g. rerflowing solder paste

Metal coated solder, e.g. for passivation of solder balls

Solder dip coating, i.e. coating printed conductors, e.g. pads by dipping in molten solder or by wave soldering

Removing excess solder on pads; removing solder bridges, e.g. for repairing or reworking

Solder filled PTH during processing (solder filled plated through-hole in the final product)

PTH for surface mount device [SMD], e.g. wherein solder flows through the PTH during mounting

Means for drawing solder, e.g. for removing excess solder from pads

Shape of solder, e.g. differing from spherical shape, different shapes due to different solder pads

Soldering with different solders, e.g. two different solders on two sides of the PCB

Molten solder just before placing the component

Self-alignment during soldering; Terminals, pads or shape of solder adapted therefor

Tacky flux, e.g. for adhering components during mounting

Wire bonding

Cold welding

Patterning and lithography; Masks; Details of resist

Patterning and lithography

Double exposure of the same photosensitive layer

Flood exposure

Diffusion patterning

Photodevelopable thick film, e.g. conductive or insulating paste

Electrographic patterning

Magnetographic patterning

Using an adhesive pattern

Patterning by phototackifying or by photopatterning adhesive

Patterning during transfer, i.e. without preformed pattern, e.g. by using a die, a programmed tool or a laser

Decalcomania, i.e. transfer of a pattern detached from its carrier before affixing the pattern to the substrate

Offset printing, i.e. transfer of a pattern from a carrier onto the substrate by using an intermediate member

Transfer of pre-fabricated insulating pattern

Continuous temporary metal layer over resist, e.g. for selective electroplating

Continuous temporary metal layer over metal pattern (reinforcing the conductive pattern characterised by the electroplating method)

Pattern for applying drops or paste; Applying a pattern made of drops or paste (using thick film techniques to apply conductive material by using a substrate with a shape pattern)

Masks

Exposure mask directly printed on the PCB

Metal used as mask for etching vias, e.g. by laser ablation

Non-printed masks

Using an artwork, i.e. a photomask for exposing photosensitive layers

Details of resist

Resist used only for applying catalyst, not for plating itself

Resist used for applying paste, ink or powder

Dual purpose resist, e.g. etch resist used as solder resist, solder resist used as plating resist

Stacked resist layers used for different processes

Double layer of resist having the same pattern

Additional resists used for the same purpose but in different areas, i.e. not stacked

Coating by resist, i.e. resist used as mask for application of insulating coating or of second resist
2203/0585 . . . Second resist used as mask for selective stripping of first resist
2203/0588 . . . Second resist used as pattern over first resist
2203/0591 . . . Organic non-polymeric coating, e.g. for inhibiting corrosion thereby preserving solderability
2203/0594 . . . Insulating resist or coating with special shaped edges
2203/0597 . . . Resist applied over the edges or sides of conductors, e.g. for protection during etching or plating (coating over pads H05K 2201/09818)
2203/06 . . . Lamination
2203/061 . . . of previously made multilayered subassemblies (laminating only or mainly similar single-sided circuit boards H05K 3/4617; laminating only or mainly similar double-sided circuit boards H05K 3/462)
2203/063 . . . of preperforated insulating layer
2203/065 . . . Binding insulating layers without adhesive, e.g. by local heating or welding, before lamination of the whole PCB
2203/066 . . . Transfer laminating of insulating material, e.g. resist as a whole layer, not as a pattern (transferring an insulating pattern H05K 2203/0537)
2203/068 . . . Features of the lamination press or of the lamination process, e.g. using special separator sheets
2203/07 . . . Treatments involving liquids, e.g. plating, rinsing
2203/0703 . . . Plating
2203/0706 . . . Inactivating or removing catalyst, e.g. on surface of resist
2203/0709 . . . Catalytic ink or adhesive for electroless plating (catalyst filler H05K 2201/0236)
2203/0713 . . . Plating poison, e.g. for selective plating or for preventing plating on resist
2203/0716 . . . Metallic plating catalysts, e.g. for direct electroplating of through holes; Sensitising or activating metallic plating catalysts
2203/072 . . . Electroless plating, e.g. finish plating or initial plating
2203/0723 . . . Electroplating, e.g. finish plating
2203/0726 . . . Electroforming, i.e. electroplating on a metallic carrier thereby forming a self-supporting structure
2203/073 . . . Displacement plating, substitution plating or immersion plating, e.g. for finish plating
2203/0733 . . . Method for plating stud vias, i.e. massive vias formed by plating the bottom of a hole without plating on the walls
2203/0736 . . . Methods for applying liquids, e.g. spraying
2203/074 . . . Features related to the fluid pressure
2203/0743 . . . Mechanical agitation of fluid, e.g. during cleaning of the conductive pattern
2203/0746 . . . Local treatment using a fluid jet, e.g. for removing or cleaning material; Providing mechanical pressure using a fluid jet
2203/075 . . . Global treatment of printed circuits by fluid spraying, e.g. cleaning a conductive pattern using nozzles
2203/0753 . . . Reversing fluid direction, e.g. in holes
2203/0756 . . . Uses of liquids, e.g. rinsing, coating, dissolving
2203/0759 . . . Forming a polymer layer by liquid coating, e.g. a non-metallic protective coating or an organic bonding layer
2203/0763 . . . Treating individual holes or single row of holes, e.g. by nozzle
2203/0766 . . . Rinsing, e.g. after cleaning or polishing a conductive pattern
2203/0769 . . . Dissolving insulating materials, e.g. coatings, not used for developing resist after exposure
2203/0773 . . . Dissolving the filler without dissolving the matrix material; Dissolving the matrix material without dissolving the filler
2203/0776 . . . Uses of liquids not otherwise provided for in H05K 2203/0759 - H05K 2203/0773
2203/0779 . . . characterised by the specific liquids involved
2203/0783 . . . Using solvent, e.g. for cleaning; Regulating solvent content of pastes or coatings for adjusting the viscosity
2203/0786 . . . Using an aqueous solution, e.g. for cleaning or during drilling of holes
2203/0789 . . . Aqueous acid solution, e.g. for cleaning or etching
2203/0793 . . . Aqueous alkaline solution, e.g. for cleaning or etching
2203/0796 . . . Oxidant in aqueous solution, e.g. permanganate
2203/08 . . . Treatments involving gases
2203/081 . . . Blowing of gas, e.g. for cooling or for providing heat during solder reflowing
2203/082 . . . Suction, e.g. for holding solder balls or components
2203/083 . . . Evaporation or sublimation of a compound, e.g. gas bubble generating agent
2203/085 . . . Using vacuum or low pressure
2203/086 . . . Using an inert gas
2203/087 . . . Using a reactive gas
2203/088 . . . Using a vapour or mist, e.g. cleaning using water vapor
2203/09 . . . Treatments involving charged particles
2203/092 . . . Particle beam, e.g. using an electron beam or an ion beam
2203/095 . . . Plasma, e.g. for treating a substrate to improve adhesion with a conductor or for cleaning holes
2203/097 . . . Corona discharge
2203/10 . . . Using electric, magnetic and electromagnetic fields; Using laser light
2203/101 . . . Using electrical induction, e.g. for heating during soldering
2203/102 . . . Using microwaves, e.g. for curing ink patterns or adhesive
2203/104 . . . Using magnetic force, e.g. to align particles or for a temporary connection during processing
2203/105 . . . Using an electrical field; Special methods of applying an electric potential (electroplating H05K 2203/0723)
2203/107 . . . Using laser light (shaping a substrate by laser ablation H05K 3/0026)
2203/108 . . . Using a plurality of lasers or laser light with a plurality of wavelengths
2203/11 . . . Treatments characterised by their effect, e.g. heating, cooling, roughening
2203/1105 . . . Heating or thermal processing not related to soldering, firing, curing or laminating, e.g. for shaping the substrate or during finish plating
2203/111 . . . Preheating, e.g. before soldering
2203/1115 . . . Resistance heating, e.g. by current through the PCB conductors or through a metallic mask
2203/1121 . . . Cooling, e.g. specific areas of a PCB being cooled during reflow soldering (details related to cooling of mounted components H05K 1/0203)
2203/1126 . . . Firing, i.e. heating a powder or paste above the melting temperature of at least one of its constituents
2203/1131 . . . Sintering, i.e. fusing of metal particles to achieve or improve electrical conductivity
2203/1136 . . . Conversion of insulating material into conductive material, e.g. by pyrolysis
2203/1142 . . . Conversion of conductive material into insulating material or into dissolvable compound
2203/1147 . . . Sealing or impregnating, e.g. of pores
2203/1152 . . . Replicating the surface structure of a sacrificial layer, e.g. for roughening
2203/1157 . . . Using means for chemical reduction
2203/1163 . . . Chemical reaction, e.g. heating solder by exothermic reaction (oxidising metal H05K 2203/0315)
2203/1168 . . . Graft-polymerization
2203/1173 . . . Differences in wettability, e.g. hydrophilic or hydrophobic areas
2203/1178 . . . Means for venting or for letting gases escape
2203/1184 . . . Underetching, e.g. etching of substrate under conductors or etching of conductor under dielectrics; Means for allowing or controlling underetching
2203/1189 . . . Pressing leads, bumps or a die through an insulating layer
2203/1194 . . . Thermal treatment leading to a different chemical state of a material, e.g. annealing for stress-relief, aging
2203/12 . . . Using specific substances
2203/121 . . . Metallo-organic compounds
2203/122 . . . Organic non-polymeric compounds, e.g. oil, wax, thiol (using solvent H05K 2203/0783)
2203/124 . . . Heterocyclic organic compounds, e.g. azole, furan
2203/125 . . . Inorganic compounds, e.g. silver salt
2203/127 . . . Lubricants, e.g. during drilling of holes
2203/128 . . . Molten metals, e.g. casting thereof, or melting by heating and excluding molten solder (spraying droplets of molten metal H05K 2203/1344)
2203/13 . . . Moulding and encapsulation; Deposition techniques; Protective layers
2203/1305 . . . Moulding and encapsulation
2203/1311 . . . Foil encapsulation, e.g. of mounted components
2203/1316 . . . Moulded encapsulation of mounted components
2203/1322 . . . Encapsulation comprising more than one layer
2203/1327 . . . Moulding over PCB locally or completely (applying non-metallic protective coatings for encapsulating mounted components H05K 3/284)
2203/1333 . . . Deposition techniques, e.g. coating
2203/1338 . . . Chemical vapour deposition
2203/1344 . . . Spraying small metal particles or droplets of molten metal
2203/135 . . . Electrophoretic deposition of insulating material
2203/1355 . . . Powder coating of insulating material
2203/1361 . . . Coating by immersion in coating bath (applying molten solder H05K 3/3468)
2203/1366 . . . Spraying coating (apparatus for coating printed circuit boards using liquid non-metallic coating compositions H05K 3/0991)
2203/1372 . . . Coating by using a liquid wave (solder dip coating H05K 2203/04)
2203/1377 . . . Protective layers
2203/1383 . . . Temporary protective insulating layer
2203/1388 . . . Temporary protective conductive layer
2203/1394 . . . Covering open PTHs, e.g. by dry film resist or by metal disc
2203/14 . . . Related to the order of processing steps
2203/1407 . . . Applying catalyst before applying plating resist
2203/1415 . . . Applying catalyst after applying plating resist
2203/1423 . . . Applying catalyst before etching, e.g. plating catalyst in holes before etching circuit
2203/143 . . . Treating holes before another process, e.g. coating holes before coating the substrate
2203/1438 . . . Treating holes after another process, e.g. coating holes after coating the substrate (metal used as mask for etching vias H05K 2203/0554)
2203/1446 . . . Treatment after insertion of lead into hole, e.g. bending, cutting, caulking or curing of adhesive but excluding soldering
2203/1453 . . . Applying the circuit pattern before another process, e.g. before filling of vias with conductive paste, before making printed resistors
2203/1461 . . . Applying or finishing the circuit pattern after another process, e.g. after filling of vias with conductive paste, after making printed resistors
2203/1469 . . . Circuit made after mounting or encapsulation of the components
2203/1476 . . . Same or similar kind of process performed in phases, e.g. coarse patterning followed by fine patterning
2203/1484 . . . Simultaneous treatments, e.g. soldering lead-in-hole components simultaneously with surface mounted components
2203/1492 . . . Periodical treatments, e.g. pulse plating of through-holes
2203/15 . . . Position of the PCB during processing
2203/1509 . . . Horizontally held PCB
2203/1518 . . . Vertically held PCB
2203/1527 . . . Oblliquely held PCB
2203/1536 . . . Temporarily stacked PCBs
2203/1545 . . . Continuous processing, i.e. involving rolls moving a band-like or solid carrier along a continuous production path
2203/1554 . . . Rotating or turning the PCB in a continuous manner
2203/1563 . . . Reversing the PCB
2203/1572 . . . Processing both sides of a PCB by the same process; Providing a similar arrangement of components on both sides; Making interlayer connections from two sides
2203/1581 . . . Treating the backside of the PCB, e.g. for heating during soldering or providing a liquid coating on the backside
2203/159 . . . Using gravitational force; Processing against the gravity direction; Using centrifugal force
2203/16 . . . Inspection; Monitoring; Aligning

H05K
Using chemical substances, e.g. colored or fluorescent, for facilitating optical or visual inspection

Testing a finished product, e.g. heat cycle testing of solder joints (patterns for electrical inspection or testing H05K 1/0268)

Monitoring a manufacturing process

Stabilizing, e.g. temperature stabilization

Alignment or registration; Control of registration

Using mechanical means for positioning, alignment or registration, e.g. using rod-in-hole alignment

Wrong mounting prevention

Post-manufacturing processes

Adding connections between adjacent pads or conductors, e.g. for modifying or repairing (programmable, customizable or modifiable circuits H05K 1/0286)

Configurations of connections suitable for easy deletion, e.g. modifiable circuits or temporary conductors for electroplating; Processes for deleting connections

Removing, replacing or disconnecting component; Easily removable component (thermal arrangements, e.g. to prevent overheating H05K 1/0201)

Demolishing, e.g. recycling, reverse engineering, destroying for security purposes; Using biodegradable materials

Details of processes not otherwise provided for in H05K 2203/01 - H05K 2203/17

Bending a rigid substrate; Breaking rigid substrates by bending (rigid circuit boards or rigid supports locally made bendable H05K 1/0278)

Protecting a component during manufacturing

Lifting the component during or after mounting; Increasing the gap between component and PCB

Sacrificial means, e.g. for temporarily filling a space for making a via or a cavity or for making rigid-flexible PCBs

**Dummy groups for the purpose of scheme testing, logistics of documents or the like**

999/00 dummy group

**WARNING**

This group and its subgroups are not real classification places. They are used only for the purpose of scheme testing, logistics of documents or the like.

999/99 dummy group